Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.129”**

**PAD FUNCTIONS:**

1. **V IN (2 bond pads)**
2. **V OUT (2 bond pads)**
3. **V OUT SENSE**
4. **ADJUST**

****

**Top Material: Al**

**Backside Material: Ti/Ni/Ag**

**Bond Pad Size: .006 X .006” min.**

**Backside Potential: DRAIN**

**Mask Ref:**

**APPROVED BY: KW DIE SIZE .057” X .036” DATE: 9/12/22**

**MFG: ANALOG POWER THICKNESS .007” P/N: AM4811P**

**DG 10.1.2**

#### Rev B, 7/19/02